FAIRCHILD SEMICONDUCTOR

IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, May 26, 2012 03:17 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
FGA90N33ATDTU	FGA90N33ATDTU	TO-3P-3			INTERNAL SUZHOU	**5.435**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	C	seconds	Not Applicable

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

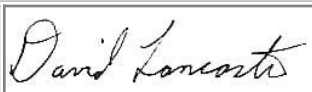
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC

7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead).

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TO-3P-3

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	41.800	Supplier		Silicon	41.800	7440-21-3	7691
Die Attach	Other Nonferrous metals & alloys	1.840	A	Lead/Lead Compounds	Lead	1.720	7439-92-1	317
			Supplier		Silver	0.028	7440-22-4	5
			Supplier		Tin	0.092	7440-31-5	17
Encapsulation	Thermoplastics	1736.800	B	Antimony/Antimony Compounds	Antimony Trioxide	43.500	1309-64-4	8004
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	52.200	6386-73-8	9605
			Supplier		Carbon Black	13.100	1333-86-4	2410
			Supplier		Epoxy Resin	348.000	29690-82-2	64034
			Supplier		Silica, vitreous	1280.000	60676-86-0	235526
Lead Frame	Copper & its alloys	3624.710	Supplier		Copper	3620.000	7440-50-8	666096
			Supplier		Phosphorus	1.090	7723-14-0	201
			Supplier		Tin	3.620	7440-31-5	666
Plating	Other Nonferrous metals & alloys	26.500	Supplier		Tin	26.500	7440-31-5	4876
Wire Bond	Aluminum & its alloys	3.000	Supplier		Aluminum	3.000	7429-90-5	552